502567671 11/13/2013

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT2613489

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DEXTER CORPORATION	08/23/2000

RECEIVING PARTY DATA

Name:	LOCTITE CORPORATION
Street Address:	1001 TROUT BROOK CROSSING
City:	ROCKY HILL
State/Country:	CONNECTICUT
Postal Code:	06067

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	5718941

CORRESPONDENCE DATA

Fax Number:
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Correspondence will be sent via US Mail when the email attempt is unsuccessful.
Correspondent Name: THERESA DOONAN
Address Line 1: HENKEL CORPORATION
Address Line 2: ONE HENKEL WAY
Address Line 4: ROCKY HILL, CONNECTICUT 06067

ATTORNEY DOCKET NUMBER:	ASSIGNMENT PROJECT
NAME OF SUBMITTER:	THERESA DOONAN
Signature:	/Theresa Doonan/
Date:	11/13/2013

Total Attachments: 10
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PATENT ASSIGNMENT

WHEREAS, Dexter Corporation (hereinafter, "Assignor"), a corporation of the State of Connecticut, having its principal business address at 1 Elm Street, Windsor Locks, Connecticut 06096-2334, U.S.A., is the owner of all rights in the patents and patent applications set forth on the attached Schedule A, and the inventions disclosed and claimed therein; and

WHEREAS, Loctite Corporation (hereinafter, "Assignee"), a Delaware corporation, having its principal business address at 1001 Trout Brook Crossing, Rocky Hill, Connecticut 06067, USA, desires to acquire the entire right, title, and interest in and to said inventions, patents and patent applications;

NOW THEREFORE, effective immediately by this document (the "Assignment"), and for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Assignor does hereby sell, assign, transfer and set over to Assignee, for its own use and enjoyment, and for the use and enjoyment of its successors, assigns and other legal representatives, as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment had not been made, the entire right, title, and interest in the United States and in all foreign countries and jurisdictions, in the patents and patent applications identified in the attached Schedule A, as well as to the inventions disclosed and claimed therein, and all continuations, divisions, reissues, reexaminations, corrections, substitutes, extensions or foreign equivalents thereof, (collectively, "Patents") and including without limitation the subject matter of all claims which may be obtained therefrom, rights of priority under International Convention for the Protection of Industrial Property, the Inter-American Convention Relating to Patents, Design and Industrial Models, and any other international agreements to which the United States adheres; together with all income, royalties, damages, claims and payments now or hereafter due or payable with respect thereto, and in and to all causes of action (either in law or in equity) and the right to sue, counterclaim, and recover for any and all legal and equitable claims for past, present and/or future infringement, damages, or other unauthorized use of the rights assigned to Assignee hereunder.

Assignor authorizes and requests the U.S. Patent and Trademark Office, or any foreign equivalent thereto, to record Assignee as owner of the Patents, and to issue any and all letters patent of the United States, or any other country, thereon to Assignee, as assignee of the entire, title and interest in, to and under the same, for the sole use and enjoyment of Assignee, its successors, assigns or other legal representative.

Assignor hereby agrees to provide cooperation and assistance to, and to execute any papers and to perform such other proper acts as Assignee, or its successors, assigns or other legal representative, may deem reasonably necessary to secure to Assignee or to its successors or assigns, the rights hereby transferred and to maintain the full value of such rights; provided, however, that the provision of the foregoing cooperation and assistance by Assignor shall be at the sole expense of Assignee.

In addition, to the extent that Assignee identifies additional Patents that are part of the Business (as defined in the Asset Purchase Agreement between Dexter Corp. and Loctite Corp. dated as of June 20, 2000), Assignor agrees to execute additional assignment agreements in forms substantially similar to this Assignment, to transfer the entire right, title and interest in such Patents to Assignee.

This Assignment may be executed in counterparts, each of which shall be deemed an original, but all of which together shall constitute one and the same instrument.

WHEREFORE, Assignor and Assignee have caused this Patent Assignment to be duly executed below, on the dates indicated, by their duly authorized officers.

DEXTER CORPORATION
("Assignor")

By:
Print Name: Bruce H. Beatt
Title: Vice President
Date: August 23, 2000

LOCTITE CORPORATION
("Assignee")

By:
Print Name: Stephen Merkel
Title: V.P.
Date: 8/23/00

STATE OF NEW YORK)
) SS.:
COUNTY OF NEW YORK)

On this 23RD day of AUGUST, 2000, before me a Notary Public in and for the County of NEW YORK in the State of NEW YORK, personally appeared BRUCE H. BEATT, to me known to be the VICE PRESIDENT of Dexter Corporation, and being duly sworn, averred that, being duly authorized, (s)he executed the foregoing Assignment as the free act and deed of said corporation for the uses and purposes set forth.

Jacqueline Y. Girard
Notary Public

JACQUELINE Y GIRARD
NOTARY PUBLIC, State of New York
No. 01GI5021753
Qualified in New York County
Commission Expires Dec. 20, ~~1999~~ 2001

My Commission expires: ___________

STATE OF NEW YORK)
) SS.:
COUNTY OF NEW YORK)

On this 23RD day of AUGUST, 2000, before me a Notary Public in and for the County of NEW YORK in the State of NEW YORK, personally appeared STEPHEN MERKEL, to me known to be the VICE PRESIDENT of Loctite Corporation, and being duly sworn, averred that, being duly authorized, (s)he executed the foregoing Assignment as the free act and deed of said corporation for the uses and purposes set forth.

Jacqueline Y. Girard
Notary Public

JACQUELINE Y GIRARD
NOTARY PUBLIC, State of New York
No. 01GI5021753
Qualified in New York County
Commission Expires Dec. 20, ~~1999~~ 2001

My Commission expires: ___________

SCHEDULE A

UNITED STATES PATENTS

Patent Title	Patent No./ Application No.	Issue or Filing Date	Status (Blank = Active)	Country	Current Assignee
Compositions Comprising Capsules for Varying Tack	60/090007			US	Dexter
Production of "Thru Vias" in Multi-Level Printed Circuit Boards by Imprinting Technology	60/076190			US	Dexter
Production of "Thru Vias" in Multi-Level Printed Circuit Boards by Imprinting Technology	09/257,911			US	Dexter
*Abrasion Resistant Coating**	*4,868,069*	*9/19/89*		*US*	*Dexter*
Adhesive Compositions with Retarding Additives	60/114941			US	Dexter
Composite Tube and Method of Manufacture	4,968,545	11/6/90		US	Dexter
Conductive Film Composite	5,928,767	7/27/99		US	Dexter
Corrosion Resistant Waterborne Adhesive Primers	5,260,357	11/9/93		US	Dexter
Curable Resins Compressing Gel Encapsulated Curing Agents	60/090006			US	Dexter
Debossable Films	5,731,086	3/24/98		US	Dexter
Encapsulating Electronic Components	4,826,896	5/2/89		US	Dexter
*Encapsulating Electronic Components**	*5,158,735*	*10/27/92*		*US*	*Dexter*
Epoxy Containing Die-Attach Compositions	5,969,036	10/19/99		US	Dexter
Expandable Films and Molded Products Therefrom	5,397,611	3/14/97		US	Dexter
Expandable Films and Molded Products Therefrom	5,234,757	8/10/93		US	Dexter
Expandable Films and Molded Products Therefrom	5,783,272	7/21/98		US	Dexter

Patent Title	Patent No./ Application No.	Issue or Filing Date	Status (Blank = Active)	Country	Current Assignee
Expandable Films and Molded Products Therefrom	5,540,963	7/30/96		US	Dexter
Flame Retardant Epoxy Molding Compound Method and Encapsulated Device	5,154,976	10/13/92		US	Dexter
Flame Retardant Epoxy Molding Compound, Method and Encapsulated Device	5,476,716	12/19/95		US	Dexter
High Viscosity Polymeric Compositions for Use in Under Filing Flip-Chip for Use in Under Filing	09/207316			US	Dexter
Hot Melt Adhesive Spray Dispenser	5,375,766	12/27/94		US	Dexter
Hydrophobic, High Tg Cycloaliphatic Epoxy Resins	09/347,091	7/1/99		US	Dexter
Inorganic Whisker Containing Impact Enhanced Prepregs and Formulations	4,992,325	2/12/91		US	Dexter
Lightning Strike Composite and Process	5,370,921	12/6/94		US	Dexter
Long Open Time Polyamide Hot Melt Adhesives	5,672,677	9/30/97		US	Dexter
Low Moisture Absorption Syntactic Foam	5,665,461	9/9/97		US	Dexter
Method for isomerization of arylpropargyl ether monomers and uses therefor	5,861,111	1/19/99		US	Dexter
*Method for Making a Conductive Film Composite**	*5,761,801*	*6/9/98*		*US*	*Dexter*
Method for Making a Debossed Conductive Film Composite	5,718,789	2/17/98		US	Dexter
Method for Making Organosilazanes	4,983,552	1/8/91		US	Dexter
Method for the preparation of lead-on-chip assemblies	5,904,500	5/18/99		US	Dexter
Method for the Preparation of Maleimides	5,973,166	10/26/99		US	Dexter

Patent Title	Patent No./ Application No.	Issue or Filing Date	Status (Blank = Active)	Country	Current Assignee
Method of Encapsulating a Semiconductor Device with a Flame Retardant Epoxy Molding Compound	5,041,254	8/20/91		US	Dexter
*Method of Manufacture Preforms**	*4,758,398*	*7/19/88*		*US*	*Dexter*
Method of Mixing Mold Release Agents	5,399,310	3/21/95		US	Dexter
Monolithic Expandable Structures, Methods of Manufacture and Composite Structures	(Not yet assigned)	7/21/00		US	Dexter
Methods of Reducing the Chloride Content of Epoxy Compounds	09/578,785			US	Dexter
Multilayer Composite Article Containing a Multimodal Combination of Filler Particles	5,397,618	3/14/95		US	Dexter
Circuit Boards	4,994,316	2/19/91		US	Dexter
Oriented Expanded Molded Products	5,660,901	8/26/97		US	Dexter
Perfluorinated Hydrocarbon Polymer-Filled Adhesive Formulations and Uses Therefor	5,717,034	2/10/98		US	Dexter
*Polyimide with Reduced Anhydride Content**	*5,175,241*	*12/29/92*		*US*	*Dexter*
Process of Making a Lightning Strike Composite	5,470,413	11/28/95		US	Dexter
Reducing Void Formation in Curable Adhesive Formulations	09/317,493			US	Dexter
Semiconductor Device Encapsulated with a Flame Retardant Epoxy Molding Compound	5,413,861	5/9/95		US	Dexter
Silver-glass paste for attachment of silicon die to ceramic substrates	4,636,254	1/13/87		US	Dexter
Thermosetting resin compositions containing maleimide and/or vinyl compounds	6,034,195	3/7/00		US	Dexter

Patent Title	Patent No./ Application No.	Issue or Filing Date	Status (Blank = Active)	Country	Current Assignee
Toughened Prepregs and Formulations	5,002,821	3/26/91		US	Dexter
Waterborne Epoxy Derivative Composition	5,378,740	1/3/95		US	Dexter
Waterborne Epoxy Derived Adhesive Primers	5,266,611	11/30/93		US	Dexter
Adhesive bonding composition with bond line limiting spacer system	5,232,962	8/3/93		US	Dexter
Die adhesion testing method and apparatus	5,313,841	5/24/94		US	Dexter
Die-attach composition comprising polycyanate ester monomer	5,358,992	10/25/94		US	Dexter
*Freeze resistant die-attach compositions**	*5,489,641*	*2/6/96*		*US*	*Dexter*
Low Temperature Glass Paste With High Metal to Glass Ratio	5,663,109	9/2/97		US	Dexter
Low temperature glass paste with improved thermal stress properties	5,543,366	8/6/96		US	Dexter
Low Temperature Glass With Improved Thermal Stress Properties and Method of Use	5,334,558	8/2/94		US	Dexter
Manually operable die attach apparatus	5,336,357	8/9/94		US	Dexter
Reducing Void Formation in Curable Adhesive Formulations	08/781,995	1/697		US	Dexter
Resinless pseudoplastic bonding compositions	5,403,389	4/4/95		US	Dexter
Resinless pseudoplastic bonding compositions	5,306,333	4/26/94		US	Dexter
Silver-glass die attach paste with reduced resin	4,968,738	11/6/90		US	Dexter
*Solvent free die-attach compositions**	*5,447,988*	*9/5/95*		*US*	*Dexter*
Adhesive Paste Containing Polymeric Resin	5,391,604	2/21/95		US	Dexter

Patent Title	Patent No./ Application No.	Issue or Filing Date	Status (Blank = Active)	Country	Current Assignee
Flame Retardant Epoxy Molding Compound	5,420,178	5/30/95		US	Dexter
Flame Retardant Epoxy Molding Compound, Method and Encapsulated Device, Method of Encapsulating a Semiconductor Device with a Flame Retardant Epoxy Molding Compound	5,338,781	8/16/94		US	Dexter
Method of Encapsulating a Semiconductor Device with a Flame Retardant Epoxy Molding Compound	5,104,604	4/14/92		US	Dexter
Acrylate Containing Formulations and Uses Therefor	08/935,352	9/22/97		US	Dexter
Bleed Resistant Cyanate Ester-containing Compositions	5,646,241	7/8/97		US	Dexter
Bleed Resistant Cyanate Ester-containing Compositions	5,753,748	5/19/98		US	Dexter
Elimination of Voids in Moisture Absorbing Boards by Use of Low Temperature Cure	08/781,995	1/6/97		US	Dexter
Elimination of Voids in Moisture Absorbing Boards by Use of Low Temperature Cure	09/317,493	5/24/99		US	Dexter
Low temperature Glass Paste with High Metal to Glass Ratio	5,663,109	9/2/97		US	Dexter
Low Viscosity Acrylate Monomer Formulations Containing Same and Uses Therefor	09/362,809	7/28/99		US	Dexter
Maleimide Containing Formulations and Uses Therefor	5,789,757	8/4/98		US	Dexter
Maleimide Containing Formulations and Uses Therefor	09/107,897	6/29/98		US	Dexter
Propargyl Ether-containing Compositions Useful for Underfill Applications	5,714,086	2/3/98		US	Dexter
Silver-glass paste with paste with poly-modal flake size distribution and quick dry vehicle	4,761,224	8/2/88		US	Dexter

Patent Title	Patent No./ Application No.	Issue or Filing Date	Status (Blank = Active)	Country	Current Assignee
Bismaleimide-divinyl Adhesive Compositions and Uses Therefor	6,034,194	3/7/00		US	Dexter

*Maintenance fees not kept up – patents will lapse.